

ARM[®] TechCon³

DESIGN TO THE POWER OF THREE



CALL FOR TECHNICAL ABSTRACTS

October 21 – 23, 2009
Santa Clara Convention Center
www.armtechcon3.com

Exciting news! The ARM Developer's Conference is expanding its scope to an engineering-oriented technical event and has been aptly re-named, **ARM TechCon³** - targeting three critical areas of design: energy efficiency, Internet everywhere and MCU and tools. ARM TechCon³ is organized by the ARM Partner ecosystem for engineers exploring or currently designing ARM hardware, software and systems design. ARM TechCon³ will serve as the premier stage to connect, instruct and communicate with the world of electronic and computer design. It will be an event that specifically enables the designer to leverage expertise from a vast array of companies in all phases of the product development cycle, from hardware to software, in these three critical areas:

Energy Efficiency and Design In an era of dwindling fossil fuels, energy efficiency is front and center in everyone's mind, particularly engineers using energy-efficient SoC strategies to minimize power requirements. The **EE** sessions will showcase the latest design and verification tools, and software and hardware for designing low-cost, low-power silicon devices.

Internet Everywhere The Internet is transforming the way people live, conduct business, manage their health, entertain themselves, and more. The **IE** sessions will be dedicated to providing the latest design strategies and tools for developing pervasive, mobile and wearable computing devices, covering the full spectrum of design and application issues.

MCU and Tools Readily-available microcontrollers and the development tools that support them are the backbone of the Embedded Industry. The **MCU and Tools** sessions will unveil new offerings and demonstrate the breadth of MCUs that are available, together with an array of hardware and software development tools enabling engineers to get their products to market more quickly than ever before.

These three important segments make up the *new* ARM TechCon³, opening a world of opportunity for you and your company. We invite you to submit an abstract for consideration and to be part of this valuable opportunity. Expand your visibility and stand out in front of decision makers, project managers, and the press.

Energy-Efficiency and Design:

These sessions will focus on energy-efficient SoC strategies; showcasing the latest design and verification tools, and software and hardware for designing low-cost, low-power silicon devices, including:

- Methodologies and standards
- Designing for low power
- Power analysis
- Power management
- Verification
- Implementation
- Services

Internet Everywhere:

The Internet opens embedded devices to a world of opportunity from straightforward data communication to full-blown Web browsing. Building convenient systems and integrating network access is not always easy. These sessions will cover the spectrum of design and application issues including:

- Network Stacks
- Platform Selection
- Security
- Cloud Computing
- Wireless Communications
- Competitive Solutions
- Rich Media Processing
- Widgets, Apps &, Flash
- Netbook Design
- Sensors, Inputs, & User Interface
- Displays, Audio, Output & Drivers
- System Integration

MCU and Tools:

Standard products put advanced technology into more hands, greatly expanding the range of end-equipment utilizing the ARM architecture. The variety of microcontrollers now available brings many more designers to the table, increasing demands for instruction, software, and development tools. These sessions will welcome MCU users, illustrate chip design, demonstrate software, and review development tools, covering:

- ARM Processor Advantages
- MCU Utilization
- Standard Products
- OS, Middleware & Packaged Software
- Programming, Development & Debugging Tools
- Multi-Core Design
- ASIC Design
- Software & Hardware Design
- Performance, Power & Price Tradeoffs
- Production & Manufacturability

You're invited to submit a presentation (or more than one) for any or for all three design segments that will educate and connect with the engineering community. We are looking for presenters with strong technical expertise to deliver a seminar session, training workshop, and/or a panel discussion.

Don't miss this exceptional, once-a-year opportunity to fully demonstrate your expertise and technology solutions by giving a face-to-face session. **There are a limited number of presentation slots available, therefore, we encourage making your submission(s) as quickly as possible—no later than July 14th.**

Due Dates:

Submission Deadline	July 14, 2009
Notification of Acceptance, Modification, Decline	July 28, 2009
Draft of Presentation	August, 14, 2009
Final Presentation	September 18, 2009

Policies Governing Accepted Presentations:

1. If there is more than one individual presenting, a lead presenter will serve as the sole point of contact for The RTC Group conference staff and is responsible for coordinating with any and/or all other presenters involved in the session. All presenters listed on the submission must be aware that they are being considered, eligible, and willing to participate as a speaker if the presentation is selected.
2. Submissions promoting specific products or companies will not be considered; presentations are not to be product pitches.
3. All presentations must have a visual component that may be projected for all session attendees to view, such as a PowerPoint slideshow or photos, graphs, charts, etc.
4. The RTC Group will determine the session's schedule, which can be at any time from October 21 through October 23, 2009. Presenters must be available on any of those days but will be notified well in advance.
5. Selected presenters will receive a complimentary full conference registration (\$795.00 value). RTC will not reimburse travel expenses or provide fees. There will be special negotiated room rates available at nearby hotels that presenters are encouraged to consider.

For further information about the ARM TechCon3 conference submissions, contact our Technical Committee.

Technical Committee:

Technical Chair:	Brian Fuller	brian-fuller@comcast.net	(415) 302-5733 (CA)
<i>Co-Chairs:</i>			
Energy Efficiency and Design:	John Donovan	john@low-powerdesign.com	(512) 673-9585 (TX)
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